



life.augmented

Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-10-23
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
------------------------------	-------------	----------------------------	-----------------

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
74LCX125YTTR	KD6R*E125I6Y	A	BO2A	2015-10-23
	Amount	UoM	Unit type	ST ECOPACK Grade
	54.82	mg	Each	ECOPACK® 3
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	5x4.4x0.9	14	gull wing	
Comment	Package: 6R TSSOP 14 BODY 4.4 PITCH 0.65; MD valid for 74LCX125YTTR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KD6R*E125I6Y					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.004	mg	supplier	die	Silicon (Si)	7440-21-3		0.968	mg	964143	17658
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	4980	91
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	1992	36
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	996	18
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	1992	36
				supplier	Passivation	Silicon Oxide	7631-86-9		0.013	mg	12948	237
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.013	mg	12948	237
				supplier	alloy	Copper (Cu)	7440-50-8		24.545	mg	946587	447738
Leadframe	Copper & its alloys	25.930	mg	supplier	alloy	Nickel (Ni)	7440-02-0		0.765	mg	29503	13955
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.038	mg	1465	693
				supplier	alloy	Silicon (Si)	7440-21-3		0.166	mg	6402	3028
				supplier	metallization	Nickel (Ni)	7440-02-0		0.285	mg	10991	5199
				supplier	metallization	Palladium (Pd)	7440-05-3		0.018	mg	694	328
				supplier	metallization	Gold (Au)	7440-57-5		0.008	mg	309	146
				supplier	metallization	Silver (Ag)	7440-22-4		0.105	mg	4049	1915
				supplier	glue	Silver (Ag)	7440-22-4		0.343	mg	881748	6257
Die attach	Other Organic Materials	0.389	mg	supplier	glue	Isobornyl Methacrylate	7534-94-3		0.019	mg	48843	347
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.019	mg	48843	347
				supplier	glue	Acrylate polymer	87320-05-6		0.008	mg	20566	146
				supplier	wire	Copper (Cu)	7440-50-8		0.127	mg	1000000	2317
Bonding wires	Other inorganic materials	0.127	mg	supplier	wire	Copper (Cu)	7440-50-8		0.127	mg	1000000	2317
Encapsulation	Other Organic Materials	27.370	mg	supplier	mold compound	Silica, vitreous	60676-86-0		24.003	mg	876982	437851
				supplier	mold compound	Epoxy resin	85954-11-6		1.095	mg	40007	19974
				supplier	mold compound	Epoxy	29690-82-2		1.095	mg	40007	19974
				supplier	mold compound	phenol resin	Proprietary		0.821	mg	29996	14976
				supplier	mold compound	additive	Proprietary		0.274	mg	10011	4998
				supplier	mold compound	carbon black	1333-86-4		0.082	mg	2996	1496